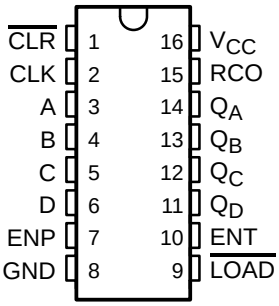
SDFS056B – MARCH 1987 – REVISED AUGUST 2001

- **Internal Look-Ahead Circuitry for Fast Counting**
- **Carry Output for N-Bit Cascading**
- **Fully Synchronous Operation for Counting**

D, DB, OR N PACKAGE
(TOP VIEW)



description

This synchronous, presettable, 4-bit binary counter has internal carry look-ahead circuitry for use in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with asynchronous (ripple-clock) counters. However, counting spikes can occur on the ripple-carry (RCO) output. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of CLK.

This counter is fully programmable. That is, it can be preset to any number between 0 and 15. Because presetting is synchronous, a low logic level at the load ($\overline{\text{LOAD}}$) input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of ENP and ENT.

The clear function is asynchronous, and a low logic level at the clear ($\overline{\text{CLR}}$) input sets all four of the flip-flop outputs to low, regardless of the levels of CLK, $\overline{\text{LOAD}}$, ENP, and ENT.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications, without additional gating. This function is implemented by the ENP and ENT inputs and an RCO output. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. RCO, thus enabled, produces a high-logic-level pulse while the count is 15 (HHHH). The high-logic-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

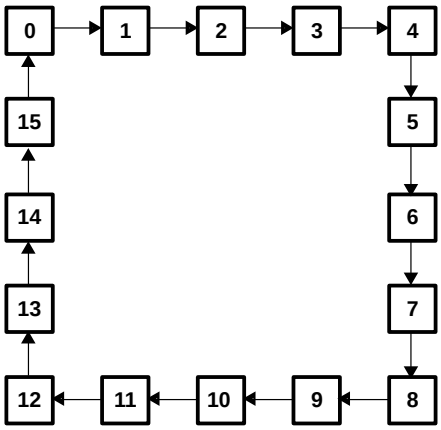
The SN74F161A features a fully independent clock circuit. Changes at ENP, ENT, or $\overline{\text{LOAD}}$ that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the setup and hold times.

ORDERING INFORMATION

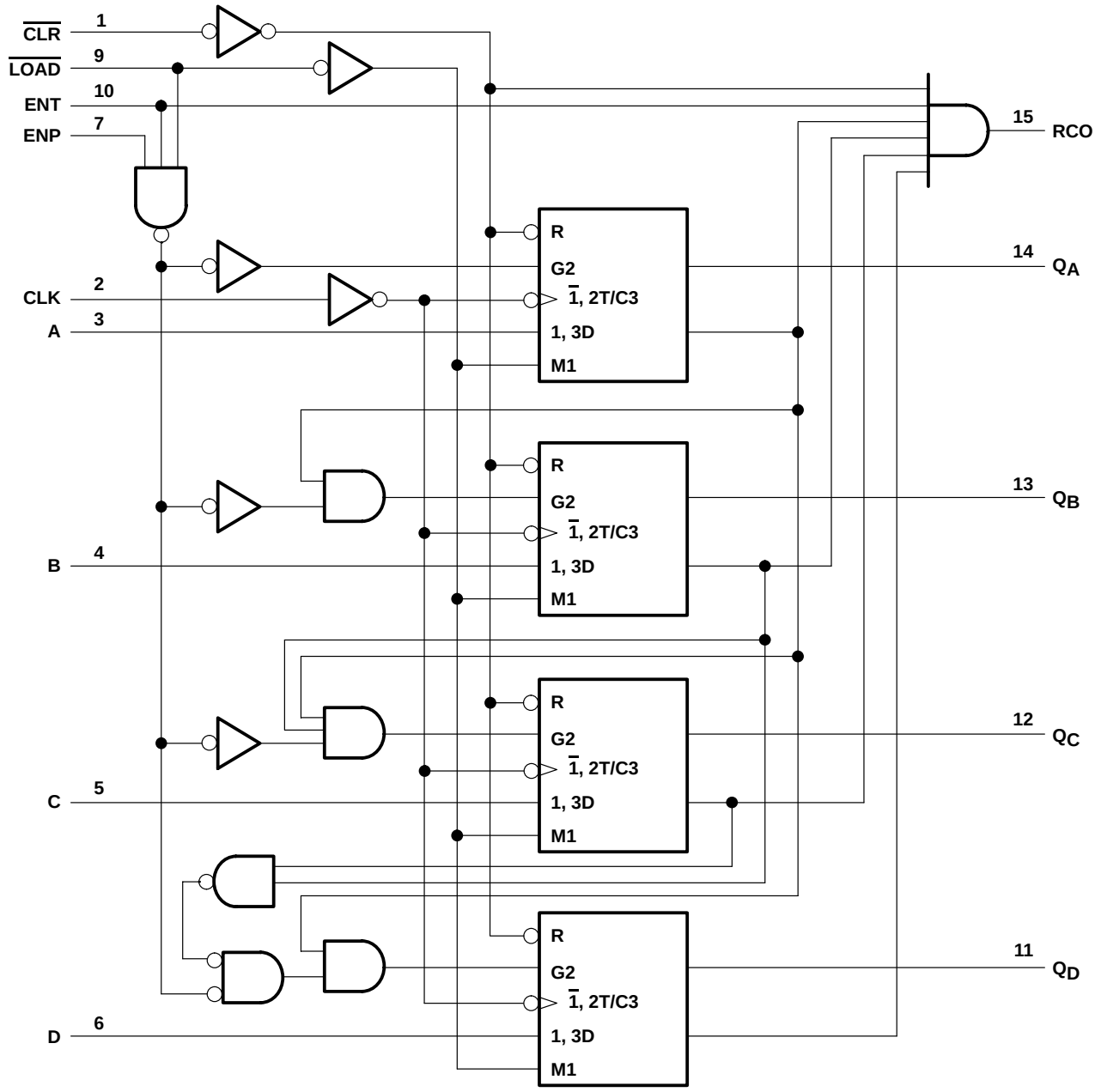
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74F161AN	SN74F161AN
	SOIC – D	Tube	SN74F161AD	F161A
		Tape and reel	SN74F161ADR	
	SSOP – DB	Tape and reel	SN74F161ADBR	F161A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

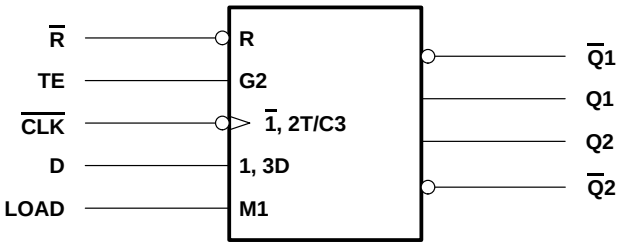
state diagram



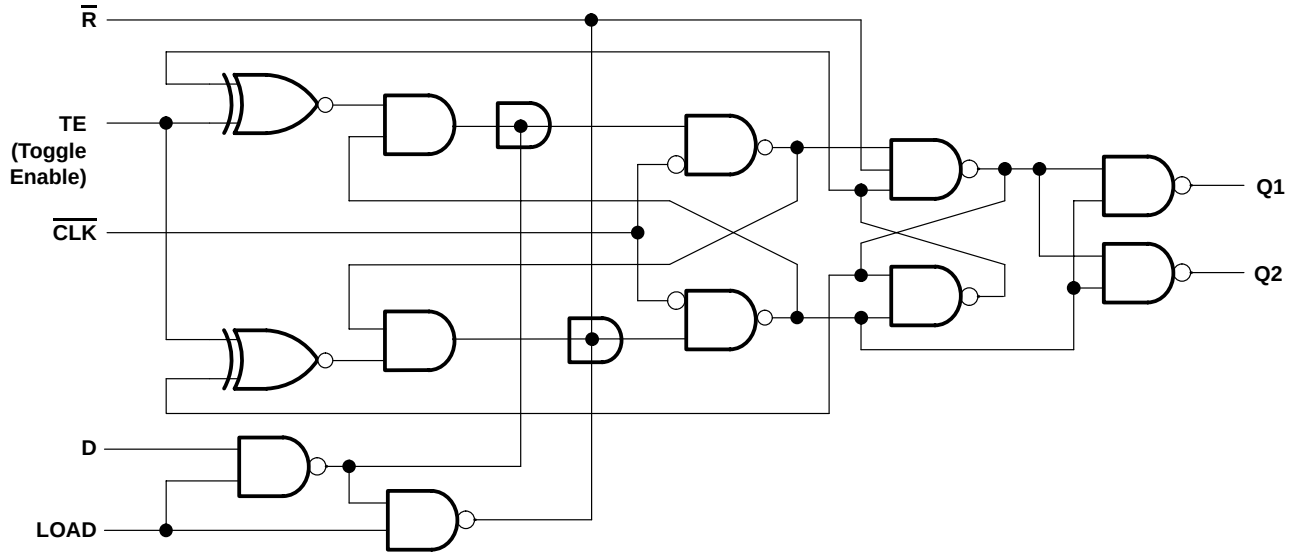
logic diagram (positive logic)



logic symbol, each flip-flop



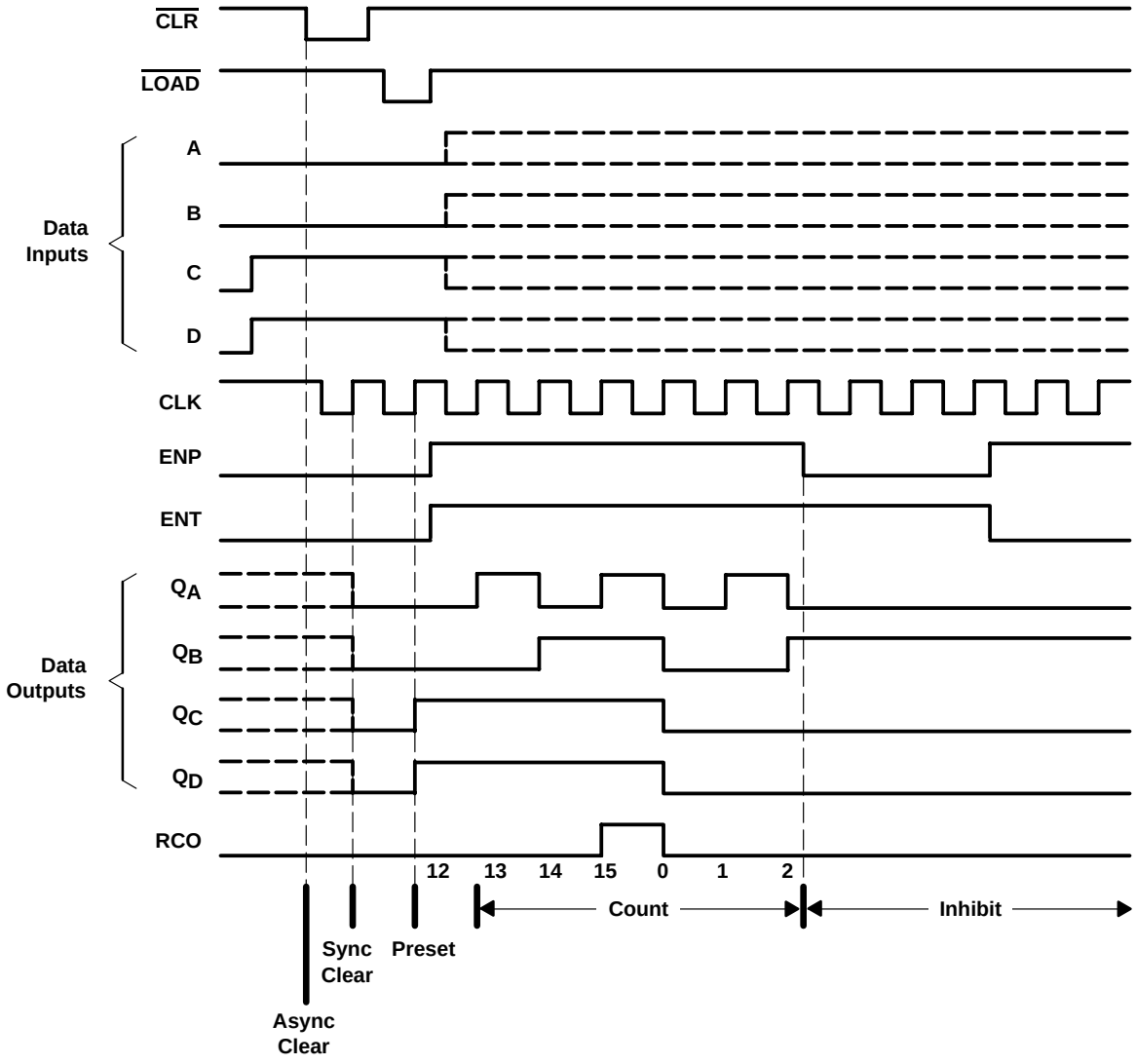
logic diagram, each flip-flop (positive logic)



typical clear, preset, count, and inhibit sequences

The following timing sequence is illustrated below:

1. Clear outputs to zero
2. Preset to binary 12
3. Count to 13, 14, 15, 0, 1, and 2
4. Inhibit



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –1.2 V to 7 V
Input current range . . . . . –30 mA to 5 mA
Voltage range applied to any output in the high state . . . . . –0.5 V to V_{CC}
Current into any output in the low state . . . . . 40 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 73°C/W
DB package . . . . . 82°C/W
N package . . . . . 67°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High-level output current			–1	mA
I_{OL}	Low-level output current			20	mA
T_A	Operating free-air temperature	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP‡	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = – 1 mA	2.5	3.4		V
		V_{CC} = 4.75 V,	I_{OH} = – 1 mA	2.7			
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 20 mA		0.3	0.5	V
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
I_{IL}	ENP, CLK, A, B, C, D	V_{CC} = 5.5 V,	V_I = 0.5 V			– 0.6	mA
	ENT, $\overline{\text{LOAD}}$					– 1.2	
	CLR					– 0.6	
I_{OS}§		V_{CC} = 5.5 V,	V_O = 0	–60		–150	mA
I_{CC}		V_{CC} = 5.5 V			37	55	mA

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V_{CC} = 5 V, T_A = 25°C		MIN	MAX	UNIT
				MIN	MAX			
f_{clock}	Clock frequency			0	100	0	90	MHz
t_w	Pulse duration	CLK high or low (loading)		5		5		ns
		CLK (counting)	High	4		4		
			Low	6		7		
		$\overline{CLR}$ low		5		5		
t_{su}	Setup time	Data before CLK↑	High or low	5		5		ns
		$\overline{LOAD}$ before CLK↑	High	11		11.5		
			Low	8.5		9.5		
		ENP and ENT before CLK↑	High	11		11.5		
			Low	5		5		
t_h	Hold time	Data after CLK↑	High or low	2		2		ns
		LOAD after CLK↑	High	2		2		
			Low	0		0		
		ENP and ENT after CLK↑	High or low	0		0		
t_{su}	Inactive-state setup time, $\overline{CLR}$ high before CLK↑†			6		6		ns

† Inactive-state setup time also is referred to as recovery time.

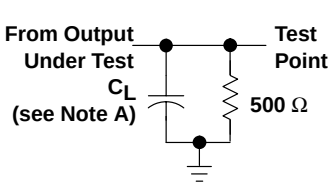
switching characteristics (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 PF, R_L = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V TO 5.5 V, C_L = 50 PF, R_L = 500 Ω, T_A = MIN TO MAX‡		UNIT
			MIN	TYP	MAX	MIN	MAX	
f_{max}			100	120		90		MHz
t_{PLH}	CLK ($\overline{LOAD}$ high)	Any Q	2.7	5.1	7.5	2.7	8.5	ns
t_{PHL}			2.7	7.1	10	2.7	11	
t_{PLH}	CLK ($\overline{LOAD}$ low)	Any Q	3.2	5.6	8.5	3.2	9.5	ns
t_{PHL}			3.2	5.6	8.5	3.2	9.5	
t_{PLH}	CLK	RCO	4.2	9.6	14	4.2	15	ns
t_{PHL}			4.2	9.6	14	4.2	15	
t_{PLH}	ENT	RCO	1.7	4.1	7.5	1.7	8.5	ns
t_{PHL}			1.7	4.1	7.5	1.7	8.5	
t_{PHL}	CLR	Any Q	4.7	8.6	12	4.7	13	ns
		RCO	3.7	7.6	10.5	3.7	11.5	

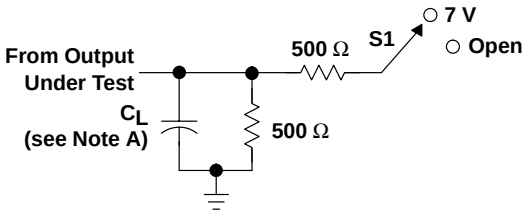
‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 4: Load circuits and waveforms are shown in Figure 1.

PARAMETER MEASUREMENT INFORMATION

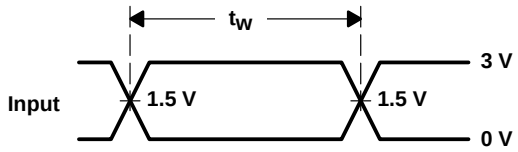


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

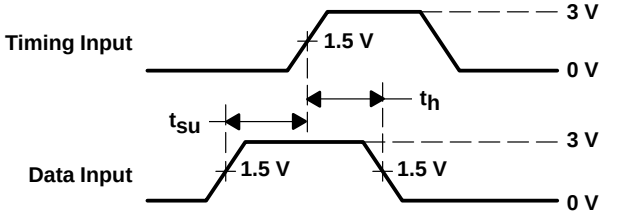


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

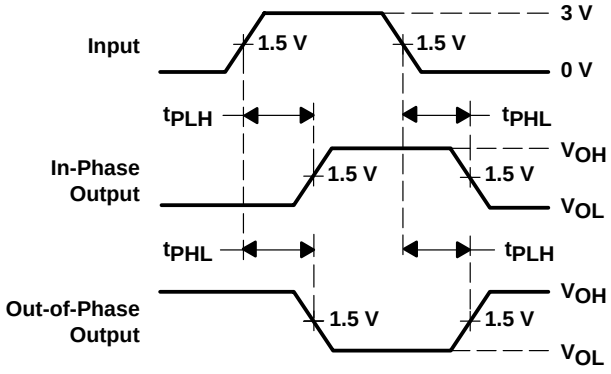
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open
Open Collector	7 V



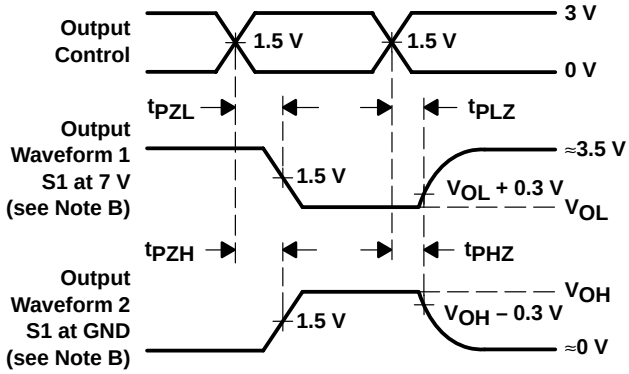
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns, duty cycle = 50%.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74F161AD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	F161A
SN74F161ADR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F161A
SN74F161ADR.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F161A
SN74F161AN	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F161AN
SN74F161AN.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F161AN
SN74F161ANSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F161A
SN74F161ANSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F161A
SN74F161ANSR.B	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F161A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

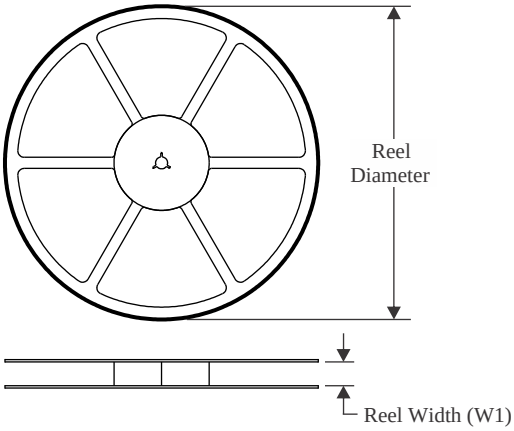
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

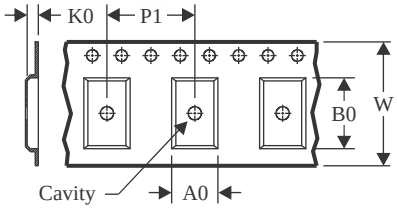
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

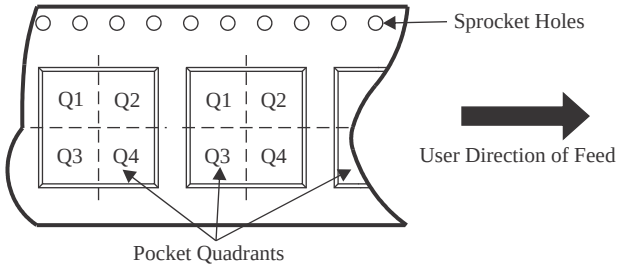


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

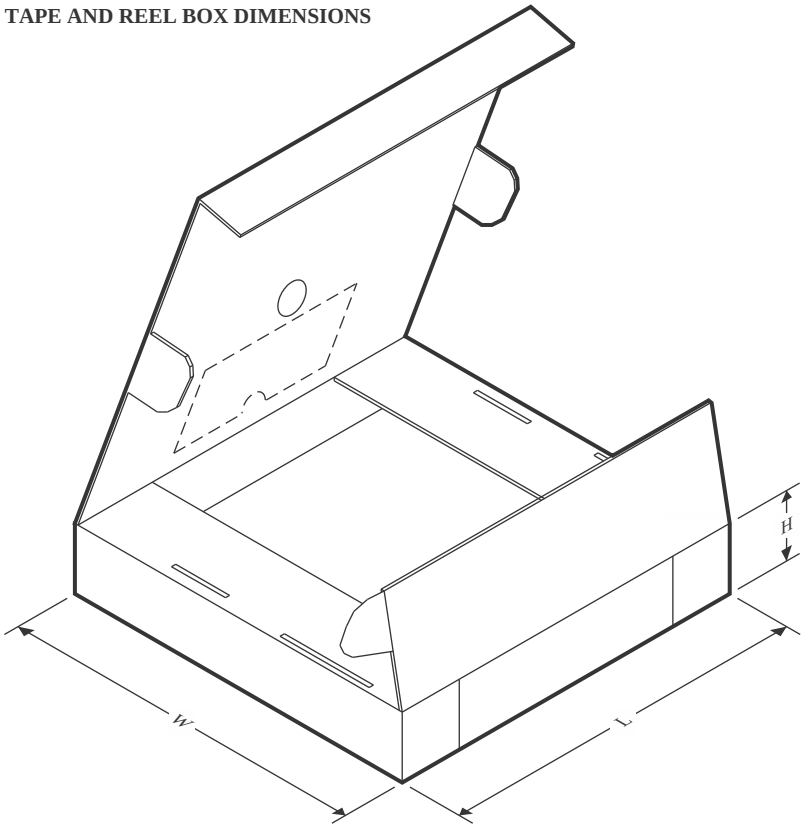
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F161ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74F161ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

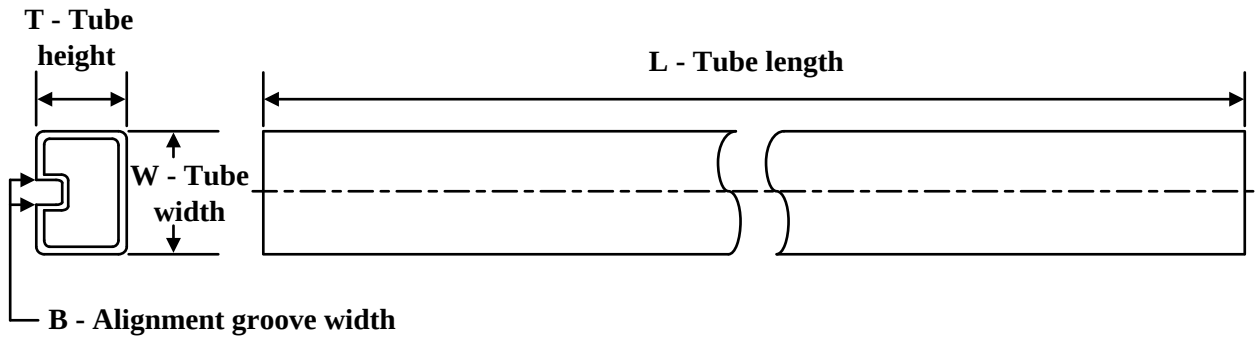
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

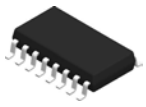
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F161ADR	SOIC	D	16	2500	353.0	353.0	32.0
SN74F161ANSR	SOP	NS	16	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F161AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74F161AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74F161AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74F161AN.A	N	PDIP	16	25	506	13.97	11230	4.32

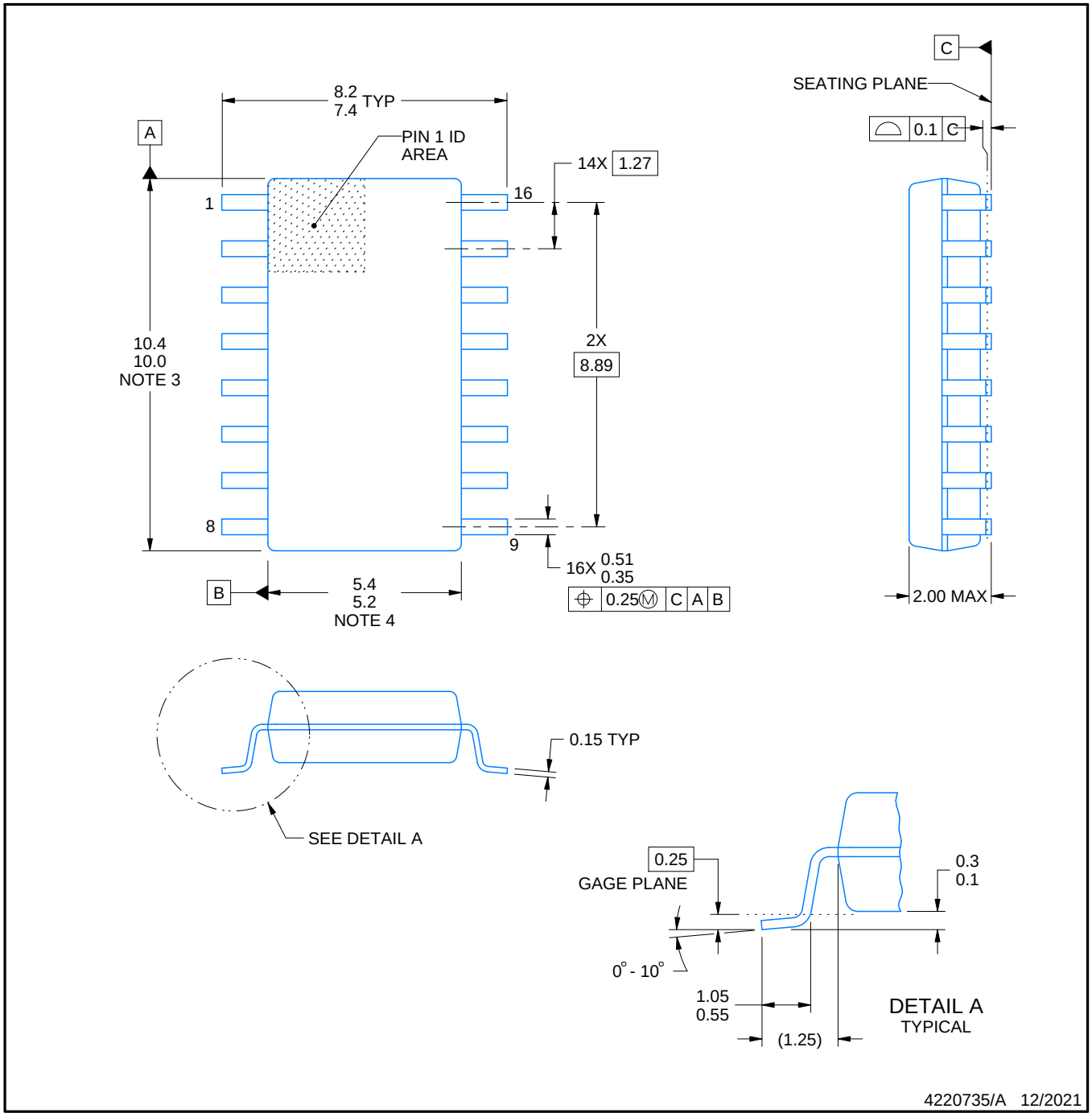


PACKAGE OUTLINE

NS0016A

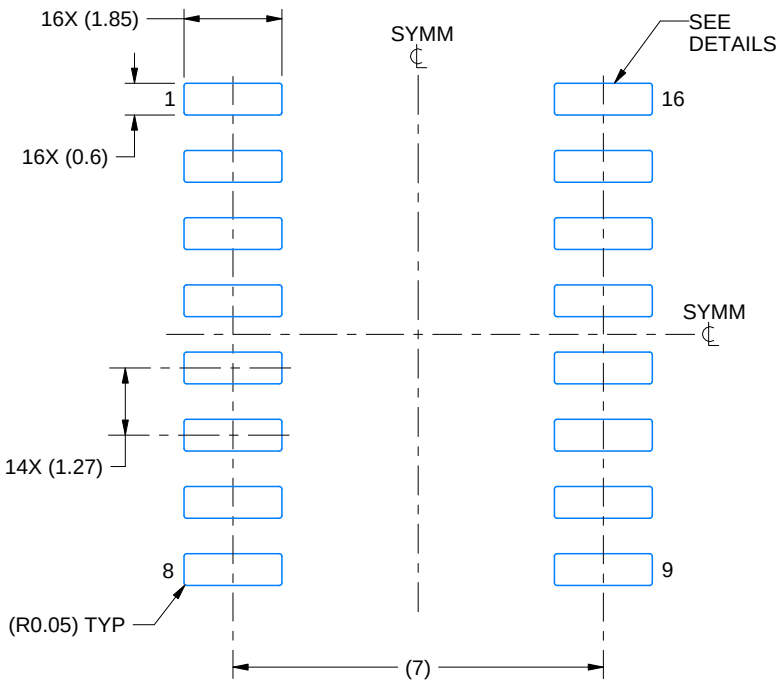
SOP - 2.00 mm max height

SOP

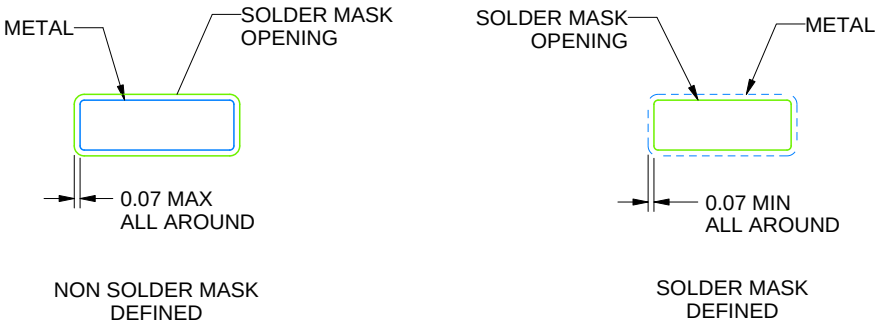


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

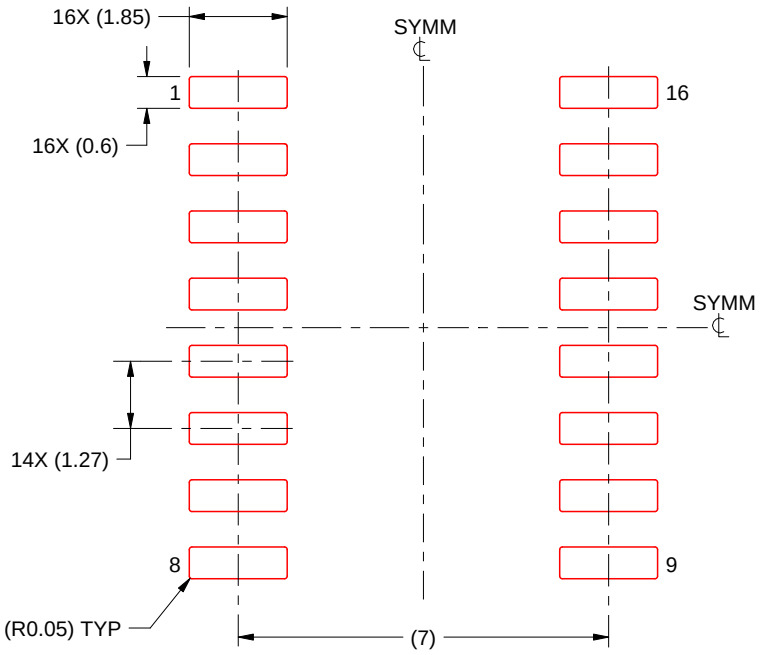
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



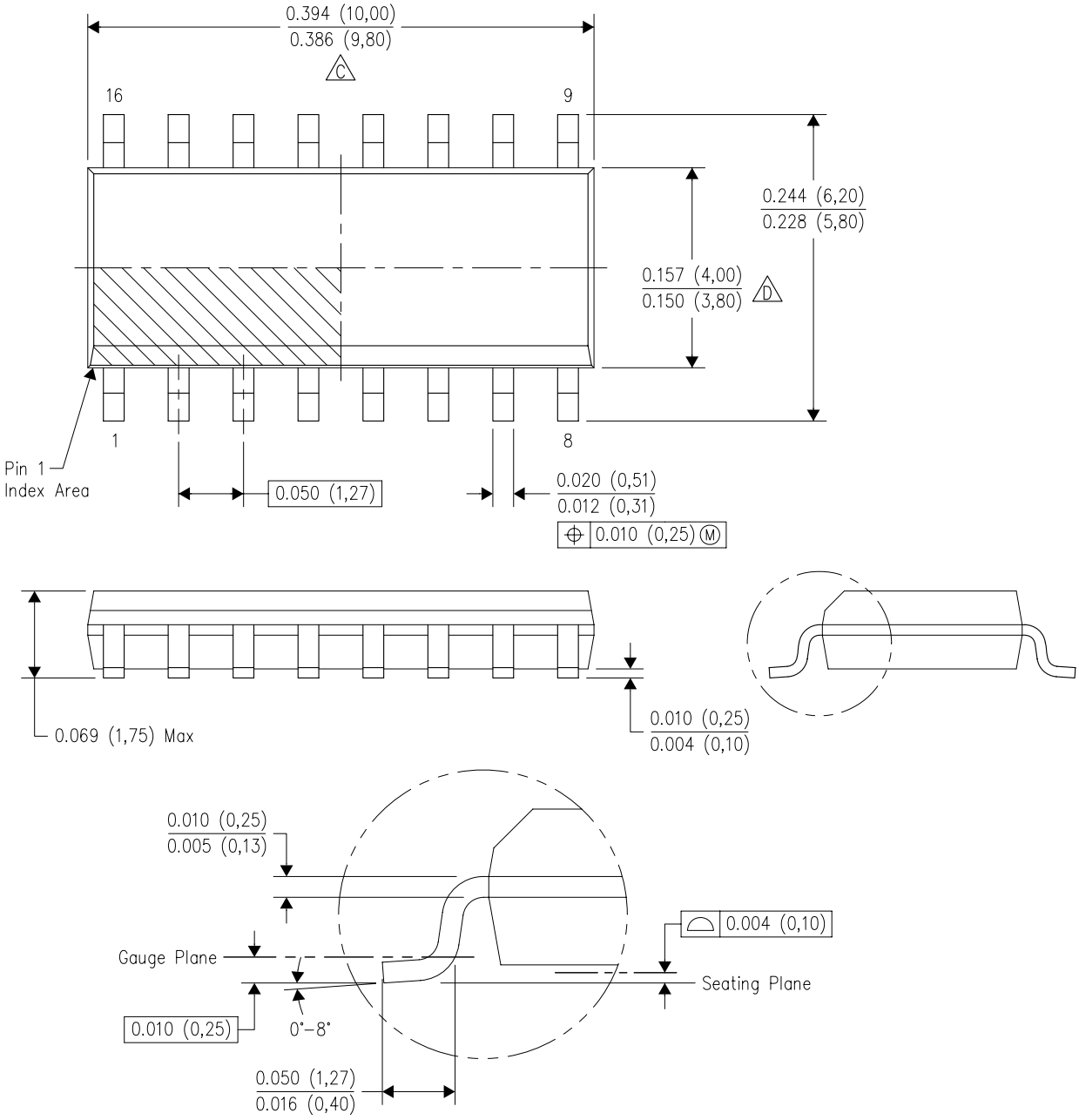
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

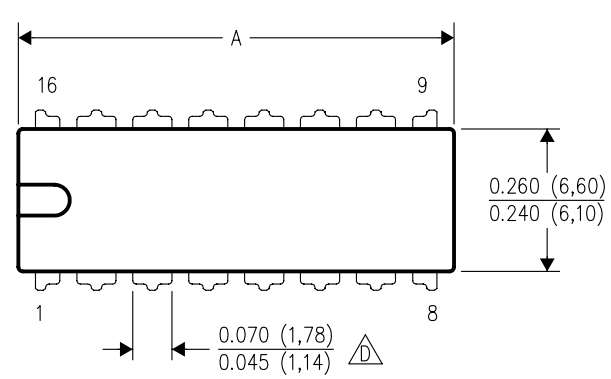


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

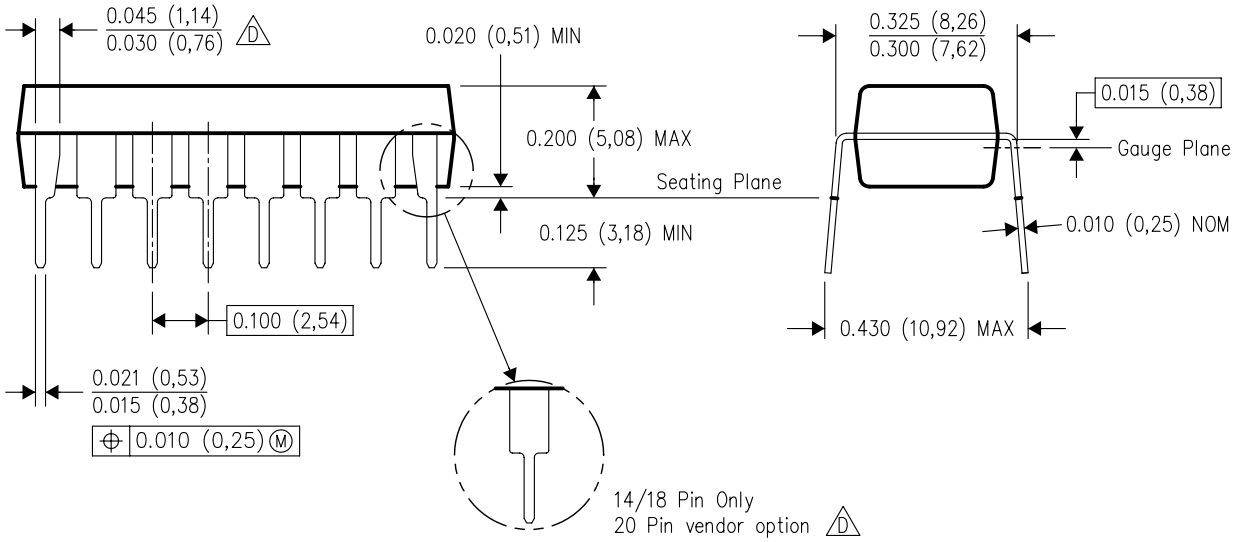
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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